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IME-03-005

January 5 , 2006

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, NY 12603

Subject: | Serial No. 10/748,736 12/30/05 |
Wong Ee Hua et al.
WAFFER LEVEL SUPER STRETCH SOLDER
| |

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation In An Application.

The following Patents and/or Publications are submitted to comply with the duty
of disclosure under CFR 1.97-1.99 and 37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States
Postal Service as first class mail in an envelope addressed to: Commissioner for Patents,
P.O. Box 1450, Alexandria, VA 22313-1450, on January 6 , 2006.

Stephen B. Ackerman, Reg. # 37761

Signature/Date SB Ackerman 1/6/06

U.S. Patent 4,545,610 to Lakritz et al., "Method for Forming Elongated Solder Connections Between a Semiconductor Device and a Supporting Substrate," discloses a process for forming elongated solder terminals to connect a plurality of pads on a semiconductor device to a corresponding plurality of pads on a supporting substrate.

U.S. Patent 6,432,744 to Amador et al., "Wafer-Scale Assembly of Chip-Size Package," discloses a wafer-scale assembly apparatus for integrated circuits and method for forming the wafer-scale assembly.

Sincerely,

A handwritten signature in black ink, appearing to read "SBA", with a long horizontal flourish extending to the right.

Stephen B. Ackerman,
Reg. No. 37761

(Use several sheets if necessary)

Application Number

10 | 748, 736

Wang, Ee Hua et al.

12/30/03

Group Art Unit

OIPE
 JAN 09 2006
 EXAMINER OF
 INTERNAL SECURITY

[illegible]

FOREIGN PATENT DOCUMENTS

[illegible]

OTHER DOCUMENTS (Including Author, Title, Date, Portmox Pages, Etc.)

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.